

ISSN 1726-5479

# SENSORS & TRANSDUCERS

3<sup>vol. 14-1  
Special</sup>  
/12



## Physical and Chemical Sensors & Wireless Sensor Networks

International Frequency Sensor Association Publishing



**Editors-in-Chief:** Sergey Y. Yurish, tel.: +34 93 413 7941, e-mail: editor@sensorsportal.com**Editors for Western Europe**Meijer, Gerard C.M., Delft University of Technology, The Netherlands  
Ferrari, Vittorio, Università di Brescia, Italy**Editor for Eastern Europe**

Sachenko, Anatoly, Ternopil State Economic University, Ukraine

**Editors for North America**Datskos, Panos G., Oak Ridge National Laboratory, USA  
Fabien, J. Josse, Marquette University, USA  
Katz, Evgeny, Clarkson University, USA**Editor South America**

Costa-Felix, Rodrigo, Inmetro, Brazil

**Editor for Africa**

Maki K.Habib, American University in Cairo, Egypt

**Editor for Asia**

Ohyama, Shinji, Tokyo Institute of Technology, Japan

**Editor for Asia-Pacific**

Mukhopadhyay, Subhas, Massey University, New Zealand

**Editorial Advisory Board**

- Abdul Rahim, Ruzairi**, Universiti Teknologi, Malaysia  
**Ahmad, Mohd Noor**, Nothern University of Engineering, Malaysia  
**Annamalai, Karthigeyan**, National Institute of Advanced Industrial Science and Technology, Japan  
**Arcega, Francisco**, University of Zaragoza, Spain  
**Arguel, Philippe**, CNRS, France  
**Ahn, Jae-Pyoung**, Korea Institute of Science and Technology, Korea  
**Arndt, Michael**, Robert Bosch GmbH, Germany  
**Ascoli, Giorgio**, George Mason University, USA  
**Atalay, Selcuk**, Inonu University, Turkey  
**Atghiaee, Ahmad**, University of Tehran, Iran  
**Augutis, Vyantas**, Kaunas University of Technology, Lithuania  
**Avachit, Patil Lalchand**, North Maharashtra University, India  
**Ayesh, Aladdin**, De Montfort University, UK  
**Azamimi, Azian binti Abdullah**, Universiti Malaysia Perlis, Malaysia  
**Bahreyni, Behraad**, University of Manitoba, Canada  
**Baliga, Shankar, B.**, General Monitors Transnational, USA  
**Baoxian, Ye**, Zhengzhou University, China  
**Barford, Lee**, Agilent Laboratories, USA  
**Barlingay, Ravindra**, RF Arrays Systems, India  
**Basu, Sukumar**, Jadavpur University, India  
**Beck, Stephen**, University of Sheffield, UK  
**Ben Bouzid, Sihem**, Institut National de Recherche Scientifique, Tunisia  
**Benachaiba, Chellali**, Universitaire de Bechar, Algeria  
**Binnie, T. David**, Napier University, UK  
**Bischoff, Gerlinde**, Inst. Analytical Chemistry, Germany  
**Bodas, Dhananjay**, IMTEK, Germany  
**Borges Carval, Nuno**, Universidade de Aveiro, Portugal  
**Bouchikhi, Benachir**, University Moulay Ismail, Morocco  
**Bousbia-Salah, Mounir**, University of Annaba, Algeria  
**Bouvet, Marcel**, CNRS – UPMC, France  
**Brudzewski, Kazimierz**, Warsaw University of Technology, Poland  
**Cai, Chenxin**, Nanjing Normal University, China  
**Cai, Qingyun**, Hunan University, China  
**Calvo-Gallego, Jaime**, Universidad de Salamanca, Spain  
**Campanella, Luigi**, University La Sapienza, Italy  
**Carvalho, Vitor**, Minho University, Portugal  
**Cecelja, Franjo**, Brunel University, London, UK  
**Cerda Belmonte, Judith**, Imperial College London, UK  
**Chakrabarty, Chandan Kumar**, Universiti Tenaga Nasional, Malaysia  
**Chakravorty, Dipankar**, Association for the Cultivation of Science, India  
**Changhai, Ru**, Harbin Engineering University, China  
**Chaudhari, Gajanan**, Shri Shivaji Science College, India  
**Chavali, Murthy**, N.I. Center for Higher Education, (N.I. University), India  
**Chen, Jiming**, Zhejiang University, China  
**Chen, Rongshun**, National Tsing Hua University, Taiwan  
**Cheng, Kuo-Sheng**, National Cheng Kung University, Taiwan  
**Chiang, Jeffrey (Cheng-Ta)**, Industrial Technol. Research Institute, Taiwan  
**Chiriac, Horia**, National Institute of Research and Development, Romania  
**Chowdhuri, Arijit**, University of Delhi, India  
**Chung, Wen-Yaw**, Chung Yuan Christian University, Taiwan  
**Corres, Jesus**, Universidad Publica de Navarra, Spain  
**Cortes, Camilo A.**, Universidad Nacional de Colombia, Colombia  
**Courtois, Christian**, Universite de Valenciennes, France  
**Cusano, Andrea**, University of Sannio, Italy  
**D'Amico, Arnaldo**, Università di Tor Vergata, Italy  
**De Stefano, Luca**, Institute for Microelectronics and Microsystem, Italy  
**Deshmukh, Kiran**, Shri Shivaji Mahavidyalaya, Barshi, India  
**Dickert, Franz L.**, Vienna University, Austria  
**Dieguez, Angel**, University of Barcelona, Spain  
**Dighavkar, C. G.**, M.G. Vidyamandir's L. V.H. College, India  
**Dimitropoulos, Panos**, University of Thessaly, Greece  
**Ding, Jianning**, Jiangsu Polytechnic University, China  
**Djordjevich, Alexandar**, City University of Hong Kong, Hong Kong  
**Donato, Nicola**, University of Messina, Italy  
**Donato, Patricio**, Universidad de Mar del Plata, Argentina  
**Dong, Feng**, Tianjin University, China  
**Drljaca, Predrag**, Instersema Sensoric SA, Switzerland  
**Dubey, Venketesh**, Bournemouth University, UK  
**Enderle, Stefan**, Univ.of Ulm and KTB Mechatronics GmbH, Germany  
**Erdem, Gursan K. Arzum**, Ege University, Turkey  
**Erkmen, Aydan M.**, Middle East Technical University, Turkey  
**Estelle, Patrice**, Insa Rennes, France  
**Estrada, Horacio**, University of North Carolina, USA  
**Faiz, Adil**, INSA Lyon, France  
**Fericean, Sorin**, Balluff GmbH, Germany  
**Fernandes, Joana M.**, University of Porto, Portugal  
**Francioso, Luca**, CNR-IMM Institute for Microelectronics and Microsystems, Italy  
**Francis, Laurent**, University Catholique de Louvain, Belgium  
**Fu, Weiling**, South-Western Hospital, Chongqing, China  
**Gaura, Elena**, Coventry University, UK  
**Geng, Yanfeng**, China University of Petroleum, China  
**Gole, James**, Georgia Institute of Technology, USA  
**Gong, Hao**, National University of Singapore, Singapore  
**Gonzalez de la Rosa, Juan Jose**, University of Cadiz, Spain  
**Granell, Annette**, Goteborg University, Sweden  
**Graff, Mason**, The University of Texas at Arlington, USA  
**Guan, Shan**, Eastman Kodak, USA  
**Guillet, Bruno**, University of Caen, France  
**Guo, Zhen**, New Jersey Institute of Technology, USA  
**Gupta, Narendra Kumar**, Napier University, UK  
**Hadjiloucas, Sillas**, The University of Reading, UK  
**Haider, Mohammad R.**, Sonoma State University, USA  
**Hashsham, Syed**, Michigan State University, USA  
**Hasni, Abdelhafid**, Bechar University, Algeria  
**Hernandez, Alvaro**, University of Alcalá, Spain  
**Hernandez, Wilmar**, Universidad Politecnica de Madrid, Spain  
**Homentcovschi, Dorel**, SUNY Binghamton, USA  
**Horstman, Tom**, U.S. Automation Group, LLC, USA  
**Hsiai, Tzung (John)**, University of Southern California, USA  
**Huang, Jeng-Sheng**, Chung Yuan Christian University, Taiwan  
**Huang, Star**, National Tsing Hua University, Taiwan  
**Huang, Wei**, PSG Design Center, USA  
**Hui, David**, University of New Orleans, USA  
**Jaffrezic-Renault, Nicole**, Ecole Centrale de Lyon, France  
**James, Daniel**, Griffith University, Australia  
**Janting, Jakob**, DELTA Danish Electronics, Denmark  
**Jiang, Liudi**, University of Southampton, UK  
**Jiang, Wei**, University of Virginia, USA  
**Jiao, Zheng**, Shanghai University, China  
**John, Joachim**, IMEC, Belgium  
**Kalach, Andrew**, Voronezh Institute of Ministry of Interior, Russia  
**Kang, Moonho**, Sunmoon University, Korea South  
**Kaniasus, Eugenijus**, Vienna University of Technology, Austria  
**Katake, Anup**, Texas A&M University, USA  
**Kausel, Wilfried**, University of Music, Vienna, Austria  
**Kavasoglu, Nese**, Mugla University, Turkey  
**Ke, Cathy**, Tyndall National Institute, Ireland  
**Khelfaoui, Rachid**, Université de Bechar, Algeria  
**Khan, Asif**, Aligarh Muslim University, Aligarh, India  
**Kim, Min Young**, Kyungpook National University, Korea South  
**Ko, Sang Choon**, Electronics. and Telecom. Research Inst., Korea South  
**Kotulska, Malgorzata**, Wroclaw University of Technology, Poland  
**Kockar, Hakan**, Balikesir University, Turkey

**Kong, Ing**, RMIT University, Australia  
**Kratz, Henrik**, Uppsala University, Sweden  
**Krishnamoorthy, Ganesh**, University of Texas at Austin, USA  
**Kumar, Arun**, University of Delaware, Newark, USA  
**Kumar, Subodh**, National Physical Laboratory, India  
**Kung, Chih-Hsien**, Chang-Jung Christian University, Taiwan  
**Lacnjevac, Caslav**, University of Belgrade, Serbia  
**Lay-Ekuakille, Aime**, University of Lecce, Italy  
**Lee, Jang Myung**, Pusan National University, Korea South  
**Lee, Jun Su**, Amkor Technology, Inc. South Korea  
**Lei, Hua**, National Starch and Chemical Company, USA  
**Li, Fengyuan (Thomas)**, Purdue University, USA  
**Li, Genxi**, Nanjing University, China  
**Li, Hui**, Shanghai Jiaotong University, China  
**Li, Xian-Fang**, Central South University, China  
**Li, Yuefa**, Wayne State University, USA  
**Liang, Yuanchang**, University of Washington, USA  
**Liawruangrath, Saisunee**, Chiang Mai University, Thailand  
**Liew, Kim Meow**, City University of Hong Kong, Hong Kong  
**Lin, Hermann**, National Kaohsiung University, Taiwan  
**Lin, Paul**, Cleveland State University, USA  
**Linderholm, Pontus**, EPFL - Microsystems Laboratory, Switzerland  
**Liu, Aihua**, University of Oklahoma, USA  
**Liu Changgeng**, Louisiana State University, USA  
**Liu, Cheng-Hsien**, National Tsing Hua University, Taiwan  
**Liu, Songqin**, Southeast University, China  
**Lodeiro, Carlos**, University of Vigo, Spain  
**Lorenzo, Maria Encarnacio**, Universidad Autonoma de Madrid, Spain  
**Lukaszewicz, Jerzy Pawel**, Nicholas Copernicus University, Poland  
**Ma, Zhanfang**, Northeast Normal University, China  
**Majstorovic, Vidosav**, University of Belgrade, Serbia  
**Malyshev, V.V.**, National Research Centre 'Kurchatov Institute', Russia  
**Marquez, Alfredo**, Centro de Investigacion en Materiales Avanzados, Mexico  
**Matay, Ladislav**, Slovak Academy of Sciences, Slovakia  
**Mathur, Prafull**, National Physical Laboratory, India  
**Maurya, D.K.**, Institute of Materials Research and Engineering, Singapore  
**Mekid, Samir**, University of Manchester, UK  
**Melnyk, Ivan**, Photon Control Inc., Canada  
**Mendes, Paulo**, University of Minho, Portugal  
**Mennell, Julie**, Northumbria University, UK  
**Mi, Bin**, Boston Scientific Corporation, USA  
**Minas, Graca**, University of Minho, Portugal  
**Moghavvemi, Mahmoud**, University of Malaya, Malaysia  
**Mohammadi, Mohammad-Reza**, University of Cambridge, UK  
**Molina Flores, Esteban**, Benemérita Universidad Autónoma de Puebla, Mexico  
**Moradi, Majid**, University of Kerman, Iran  
**Morello, Rosario**, University "Mediterranea" of Reggio Calabria, Italy  
**Mounir, Ben Ali**, University of Sousse, Tunisia  
**Mrad, Nezih**, Defence R&D, Canada  
**Mulla, Imtiaz Sirajuddin**, National Chemical Laboratory, Pune, India  
**Nabok, Aleksey**, Sheffield Hallam University, UK  
**Neelamegam, Periasamy**, Sastra Deemed University, India  
**Neshkova, Milka**, Bulgarian Academy of Sciences, Bulgaria  
**Oberhammer, Joachim**, Royal Institute of Technology, Sweden  
**Ould Lahoucine, Cherif**, University of Guelma, Algeria  
**Pamidighanta, Sayanu**, Bharat Electronics Limited (BEL), India  
**Pan, Jisheng**, Institute of Materials Research & Engineering, Singapore  
**Park, Joon-Shik**, Korea Electronics Technology Institute, Korea South  
**Penza, Michele**, ENEA C.R., Italy  
**Pereira, Jose Miguel**, Instituto Politecnico de Seteбал, Portugal  
**Petsev, Dimiter**, University of New Mexico, USA  
**Pogacnik, Lea**, University of Ljubljana, Slovenia  
**Post, Michael**, National Research Council, Canada  
**Prance, Robert**, University of Sussex, UK  
**Prasad, Ambika**, Gulbarga University, India  
**Prateepasen, Asa**, Kingmoungut's University of Technology, Thailand  
**Pugno, Nicola M.**, Politecnico di Torino, Italy  
**Pullini, Daniele**, Centro Ricerche FIAT, Italy  
**Pumera, Martin**, National Institute for Materials Science, Japan  
**Radhakrishnan, S.**, National Chemical Laboratory, Pune, India  
**Rajanna, K.**, Indian Institute of Science, India  
**Ramadan, Qasem**, Institute of Microelectronics, Singapore  
**Rao, Basuthkar**, Tata Inst. of Fundamental Research, India  
**Raouf, Kosai**, Joseph Fourier University of Grenoble, France  
**Rastogi Shiva, K.**, University of Idaho, USA  
**Reig, Candid**, University of Valencia, Spain  
**Restivo, Maria Teresa**, University of Porto, Portugal  
**Robert, Michel**, University Henri Poincare, France  
**Rezazadeh, Ghader**, Urmia University, Iran  
**Royo, Santiago**, Universitat Politecnica de Catalunya, Spain  
**Rodriguez, Angel**, Universidad Politecnica de Cataluna, Spain  
**Rothberg, Steve**, Loughborough University, UK  
**Sadana, Ajit**, University of Mississippi, USA  
**Sadeghian Marnani, Hamed**, TU Delft, The Netherlands  
**Sapozhnikova, Ksenia**, D.I.Mendeleyev Institute for Metrology, Russia  
**Sandacci, Serghei**, Sensor Technology Ltd., UK  
**Saxena, Vibha**, Bbhba Atomic Research Centre, Mumbai, India  
**Schneider, John K.**, Ultra-Scan Corporation, USA  
**Sengupta, Deepak**, Advance Bio-Photonics, India  
**Seif, Selemeni**, Alabama A & M University, USA  
**Seifter, Achim**, Los Alamos National Laboratory, USA  
**Shah, Kriyang**, La Trobe University, Australia  
**Sankarraj, Anand**, Detector Electronics Corp., USA  
**Silva Girao, Pedro**, Technical University of Lisbon, Portugal  
**Singh, V. R.**, National Physical Laboratory, India  
**Slomovitz, Daniel**, UTE, Uruguay  
**Smith, Martin**, Open University, UK  
**Soleymanpour, Ahmad**, Damghan Basic Science University, Iran  
**Somani, Prakash R.**, Centre for Materials for Electronics Technol., India  
**Sridharan, M.**, Sastra University, India  
**Srinivas, Talabattula**, Indian Institute of Science, Bangalore, India  
**Srivastava, Arvind K.**, NanoSonix Inc., USA  
**Stefan-van Staden, Raluca-Ioana**, University of Pretoria, South Africa  
**Stefanescu, Dan Mihai**, Romanian Measurement Society, Romania  
**Sumriddetchka, Sarun**, National Electronics and Computer Technology Center, Thailand  
**Sun, Chengliang**, Polytechnic University, Hong-Kong  
**Sun, Dongming**, Jilin University, China  
**Sun, Junhua**, Beijing University of Aeronautics and Astronautics, China  
**Sun, Zhiqing**, Central South University, China  
**Suri, C. Raman**, Institute of Microbial Technology, India  
**Sysoev, Victor**, Saratov State Technical University, Russia  
**Szewczyk, Roman**, Industrial Research Inst. for Automation and Measurement, Poland  
**Tan, Ooi Kiang**, Nanyang Technological University, Singapore  
**Tang, Dianping**, Southwest University, China  
**Tang, Jaw-Luen**, National Chung Cheng University, Taiwan  
**Teker, Kasif**, Frostburg State University, USA  
**Thirunavukkarasu, I.**, Manipal University Karnataka, India  
**Thumavanam Pad, Kartik**, Carnegie Mellon University, USA  
**Tian, Gui Yun**, University of Newcastle, UK  
**Tsiantos, Vassilios**, Technological Educational Institute of Kaval, Greece  
**Tsigara, Anna**, National Hellenic Research Foundation, Greece  
**Twomey, Karen**, University College Cork, Ireland  
**Valente, Antonio**, University, Vila Real, - U.T.A.D., Portugal  
**Vanga, Raghav Rao**, Summit Technology Services, Inc., USA  
**Vaseashta, Ashok**, Marshall University, USA  
**Vazquez, Carmen**, Carlos III University in Madrid, Spain  
**Vieira, Manuela**, Instituto Superior de Engenharia de Lisboa, Portugal  
**Vigna, Benedetto**, STMicroelectronics, Italy  
**Vrba, Radimir**, Brno University of Technology, Czech Republic  
**Wandelt, Barbara**, Technical University of Lodz, Poland  
**Wang, Jiangping**, Xi'an Shiyou University, China  
**Wang, Kedong**, Beihang University, China  
**Wang, Liang**, Pacific Northwest National Laboratory, USA  
**Wang, Mi**, University of Leeds, UK  
**Wang, Shinn-Fwu**, Ching Yun University, Taiwan  
**Wang, Wei-Chih**, University of Washington, USA  
**Wang, Wensheng**, University of Pennsylvania, USA  
**Watson, Steven**, Center for NanoSpace Technologies Inc., USA  
**Weiping, Yan**, Dalian University of Technology, China  
**Wells, Stephen**, Southern Company Services, USA  
**Wolkenberg, Andrzej**, Institute of Electron Technology, Poland  
**Woods, R. Clive**, Louisiana State University, USA  
**Wu, DerHo**, National Pingtung Univ. of Science and Technology, Taiwan  
**Wu, Zhaoyang**, Hunan University, China  
**Xiu Tao, Ge**, Chuzhou University, China  
**Xu, Lisheng**, The Chinese University of Hong Kong, Hong Kong  
**Xu, Sen**, Drexel University, USA  
**Xu, Tao**, University of California, Irvine, USA  
**Yang, Dongfang**, National Research Council, Canada  
**Yang, Shuang-Hua**, Loughborough University, UK  
**Yang, Wuqiang**, The University of Manchester, UK  
**Yang, Xiaoling**, University of Georgia, Athens, GA, USA  
**Yaping Dan**, Harvard University, USA  
**Ymeti, Aurel**, University of Twente, Netherland  
**Yong Zhao**, Northeastern University, China  
**Yu, Haihu**, Wuhan University of Technology, China  
**Yuan, Yong**, Massey University, New Zealand  
**Yufera Garcia, Alberto**, Seville University, Spain  
**Zakaria, Zulkarnay**, University Malaysia Perlis, Malaysia  
**Zagnoni, Michele**, University of Southampton, UK  
**Zamani, Cyrus**, Universitat de Barcelona, Spain  
**Zeni, Luigi**, Second University of Naples, Italy  
**Zhang, Minglong**, Shanghai University, China  
**Zhang, Qintao**, University of California at Berkeley, USA  
**Zhang, Weiping**, Shanghai Jiao Tong University, China  
**Zhang, Wenming**, Shanghai Jiao Tong University, China  
**Zhang, Xueji**, World Precision Instruments, Inc., USA  
**Zhong, Haoxiang**, Henan Normal University, China  
**Zhu, Qing**, Fujifilm Dimatix, Inc., USA  
**Zorzano, Luis**, Universidad de La Rioja, Spain  
**Zourob, Mohammed**, University of Cambridge, UK

# Contents

Volume 14-1  
Special Issue  
March 2012

www.sensorsportal.com

ISSN 1726-5479

## Research Articles

<b>Physical and Chemical Sensors &amp; Wireless Sensor Networks (Foreword)</b> <i>Sergey Y. Yurish, Petre Dini</i> .....	1
<b>From Smart to Intelligent Sensors: A Case Study</b> <i>Vincenzo Di Lecce, Marco Calabrese</i> .....	1
<b>Smart Optoelectronic Sensors and Intelligent Sensor Systems</b> <i>Sergey Y. Yurish</i> .....	18
<b>Accelerometer and Magnetometer Based Gyroscope Emulation on Smart Sensor for a Virtual Reality Application</b> <i>Baptiste Delporte, Laurent Perroton, Thierry Grandpierre and Jacques Trichet</i> .....	32
<b>Top-Level Simulation of a Smart-Bolometer Using VHDL Modeling</b> <i>Matthieu Denoual and Patrick Attia</i> .....	48
<b>A Novel Liquid Level Sensor Design Using Laser Optics Technology</b> <i>Mehmet Emre Erdem and Doğan Güneş</i> .....	65
<b>Recognition of Simple Gestures Using a PIR Sensor Array</b> <i>Piotr Wojtczuk, Alistair Armitage, T. David Binnie, Tim Chamberlain</i> .....	83
<b>Sinusoidal Calibration of Force Transducers Using Electrodynamic Shaker Systems</b> <i>Christian Schlegel, Gabriela Kiekenap, Bernd Glöckner, Rolf Kumme</i> .....	95
<b>Experimental Validation of a Sensor Monitoring Ice Formation over a Road Surface</b> <i>Amedeo Troiano, Eros Pasero, Luca Mesin</i> .....	112
<b>Acoustic Emission Sensing of Structures under Stretch</b> <i>Irinela Chilibon, Marian Mogildea, George Mogildea</i> .....	122
<b>Differential Search Coils Based Magnetometers: Conditioning, Magnetic Sensitivity, Spatial Resolution</b> <i>Timofeeva Maria, Allegre Gilles, Robbes Didier, Flament Stéphane</i> .....	134
<b>Silicon Photomultipliers: Dark Current and its Statistical Spread</b> <i>Roberto Pagano, Sebania Libertino, Giusy Valvo, Alfio Russo, Delfo Nunzio Sanfilippo, Giovanni Condorelli, Clarice Di Martino, Beatrice Carbone, Giorgio Fallica and Salvatore Lombardo</i> .....	151
<b>An Integrated Multimodal Sensor for the On-site Monitoring of the Water Content and Nutrient Concentration of Soil by Measuring the Phase and Electrical Conductivity</b> <i>Masato Futagawa, Md. Iqramul Hussain, Keita Kamado, Fumihiko Dasai, Makoto Ishida, Kazuaki Sawada</i> .....	160
<b>Design and Evaluation of Impedance Based Sensors for Micro-condensation Measurement under Field and Climate Chamber Conditions</b> <i>Geert Brokmann, Michael Hintz, Barbara March and Arndt Steinke</i> .....	174

<b>A Parallel Sensing Technique for Automatic Bilayer Lipid Membrane Arrays Monitoring</b> <i>Michele Rossi, Federico Thei and Marco Tartagni</i> .....	185
<b>Development of Acoustic Devices Functionalized with Cobalt Corroles or Metalloporphyrines for the Detection of Carbon Monoxide at Low Concentration</b> <i>Meddy Vanotti, Virginie Blondeau-Patissier, David Rabus, Jean-Yves Rauch, Jean-Michel Barbe, Sylvain Ballandras</i> .....	197
<b>Group IV Materials for High Performance Methane Sensing in Novel Slot Optical Waveguides at 2.883 <math>\mu\text{m}</math> and 3.39 <math>\mu\text{m}</math></b> <i>Vittorio M. N. Passaro, Benedetto Troia and Francesco De Leonardis</i> .....	212
<b>The Impact of High Dielectric Permittivity on SOI Double-Gate Mosfet Using Nextnano Simulator</b> <i>Samia Slimani, Bouaza Djellouli</i> .....	231
<b>A Novel Sensor for VOCs Using Nanostructured ZnO and MEMS Technologies</b> <i>H. J. Pandya, Sudhir Chandra and A. L. Vyas</i> .....	244
<b>La<sub>0.7</sub>Sr<sub>0.3</sub>MnO<sub>3</sub> Thin Films for Magnetic and Temperature Sensors at Room Temperature</b> <i>Sheng Wu, Dalal Fadil, Shuang Liu, Ammar Aryan, Benoit Renault, Jean-Marc Routoure, Bruno Guillet, Stéphane Flament, Pierre Langlois and Laurence Méchin</i> .....	253
<b>Cell-Culture Real Time Monitoring Based on Bio-Impedance Measurements</b> <i>Paula Daza, Daniel Cañete, Alberto Olmo, Juan A. García and Alberto Yúfera</i> .....	266

Authors are encouraged to submit article in MS Word (doc) and Acrobat (pdf) formats by e-mail: editor@sensorsportal.com  
Please visit journal's webpage with preparation instructions: <http://www.sensorsportal.com/HTML/DIGEST/Submission.htm>

International Frequency Sensor Association (IFSA).

## BioMEMS 2010

Yole's BioMEMS report 2010-2015

IFSA offers  
a SPECIAL PRICE

### Microsystems Devices Driving Healthcare Applications

**The BioMEMS 2010 report** is a robust analysis of the Micro Devices with the most advances to develop solutions for vital bio-medical applications. The devices considered are:

Pressure sensors	Microfluidic chips
Silicon microphones	Microdispensers for drug delivery
Accelerometers	Flow meters
Gyroscopes	Infrared temperature sensors
Optical MeMs and image sensors	Emerging MeMs (rfID, strain sensors, energy harvesting)

Also addressed are the regulation aspects for medical device development.

<http://www.sensorsportal.com/HTML/BioMEMS.htm>



The 3rd International Conference on Sensor Device Technologies and Applications



## SENSORDEVICES 2012

19 - 24 August 2012 - Rome, Italy

Deadline for papers: 5 April 2012



**Tracks:** Sensor devices - Ultrasonic and Piezosensors - Photonics - Infrared - Geosensors - Sensor device technologies - Sensors signal conditioning and interfacing circuits - Medical devices and sensors applications - Sensors domain-oriented devices, technologies, and applications - Sensor-based localization and tracking technologies

<http://www.iaia.org/conferences2012/SENSORDEVICES12.html>

The 6th International Conference on Sensor Technologies and Applications



## SENSORCOMM 2012

19 - 24 August 2012 - Rome, Italy

Deadline for papers: 5 April 2012



**Tracks:** Architectures, protocols and algorithms of sensor networks - Energy, management and control of sensor networks - Resource allocation, services, QoS and fault tolerance in sensor networks - Performance, simulation and modelling of sensor networks - Security and monitoring of sensor networks - Sensor circuits and sensor devices - Radio issues in wireless sensor networks - Software, applications and programming of sensor networks - Data allocation and information in sensor networks - Deployments and implementations of sensor networks - Under water sensors and systems - Energy optimization in wireless sensor networks

<http://www.iaia.org/conferences2012/SENSORCOMM12.html>

The 5th International Conference on Advances in Circuits, Electronics and Micro-electronics



## CENICS 2012

19 - 24 August 2012 - Rome, Italy

Deadline for papers: 5 April 2012



**Tracks:** Semiconductors and applications - Design, models and languages - Signal processing circuits - Arithmetic computational circuits - Microelectronics - Electronics technologies - Special circuits - Consumer electronics - Application-oriented electronics

<http://www.iaia.org/conferences2012/CENICS12.html>

## A Novel Liquid Level Sensor Design Using Laser Optics Technology

<sup>1</sup>Mehmet Emre ERDEM and <sup>2</sup>Doğan GÜNEŞ

<sup>1</sup>Institute of Science and Technology, Istanbul Technical University

<sup>2</sup>Energy Systems Engineering Department, Istanbul Bilgi University  
Istanbul, Turkey

E-mail: [dogan.gunes@bilgi.edu.tr](mailto:dogan.gunes@bilgi.edu.tr)

*Received: 13 October 2011 / Accepted: 20 December 2011 / Published: 12 March 2012*

---

**Abstract:** New materials and technological developments in electronics and computers have changed all of the industries, as well as the world itself. These technological advancements have evolved automotive industry by redefining the concepts like: performance, efficiency, fuel consumption, driving dynamics, ergonomics etc. to a level far beyond expected. Oil level in an internal combustion engine today is estimated by use of ultrasonic sensor devices. In this paper, the development stages of a novel liquid level sensing device and the development strategy is presented in detail. Several prototypes of the proposed new sensor are developed and tested. Experimental results indicate that by using the laser optics technology, sensitivity ranges of 0.0266 Pa in air pressure and 0.0064 mm water height measurements may be achieved. *Copyright* © 2012 IFSA.

**Keywords:** Sensor(s), Laser optics, Liquid level sensor, Engine oil, Whispering Gallery Mode (WGM).

---

### 1. Introduction

Oil sensors and analyzers are used in automotive and industrial applications to gather or send valuable information to ensure that the level of the engine oil does not become dangerously low without being noticed. The sensor monitors the oil level continuously during the entire engine operation, which means that the oil level can be prevented from falling below the minimum level during operation, which in turn means the oil film is not interrupted (which would lead to engine damage). Secondary influences such as the slope of the vehicle's lateral and longitudinal accelerations are compensated by the vehicle control unit calculating a mean value [1].

There are many oil level sensors in automotive, but most common approaches are ultrasound and resistance sensors [1, 2]. Sensors using a resistance wire work with the principle of changing resistance and temperature of the wire between under and over the liquid. Sensor sends a current to the wire, and the output voltage differs by changing liquid levels.

The ultrasonic level sensor, however, works on the principle of measuring the time-frame between transmitting and receiving of ultrasound waves. The ultrasound wave travels through material [2]. The sensors emit high frequency (20 to 200 kHz) acoustic waves that are reflected back to and detected by the emitting transducer affected by the changing speed of sound according to moisture, temperature, and pressures. Correction factors can be applied to the measurement level to improve the accuracy of measurement. Ultrasonic sensors have advantages in dynamic measurements; nevertheless they are more complex and more expensive when compared with the resistance wire type level sensors.

A new liquid level sensor design, aiming to place the ultrasonic sensor within the oil level pan to avoid external damage effects is presented in [1]. In this paper, a novel design using laser optic technology based on Whispering Gallery Mode (WGM) theory into liquid level sensing is presented [3, 4].

## **2. Liquid Level Sensor Development History**

An ultrasonic wave propagation method was developed in 2001 by BF Goodrich airplane advanced sensors department [5]. The principle is the same with the study before, sending and collecting ultrasonic waves, and finding the liquid levels according to the wave transfer times.

A totally different method is the usage of fiber optics in liquid level measurement [6]. Fiber optic cables reflect the laser/light signal when in the air. However, when the density difference reduces, it transfers the laser light to the liquid environment and thus the sensor detects the liquid environment.

Fiber optics is used again in another study [6]. The methodology used is as follows. While in air, most of the light rays reflect back, but in water light rays continue their way. The decrease in the level of reflected signals indicates that the optical fiber tip is inside the water. The simplicity of the methodology implies that within the material property boundaries (between  $-20^{\circ}\text{C}$  and  $+70^{\circ}\text{C}$ ) usage of optical fibers is easy, accurate and inexpensive.

In the case for automotive engine applications however, although all of the above methods have different advantages, a new method is required. The design must have high precision, and needs to be small enough to be located into the engine and must be durable enough for working under flammable liquids or gasses safely.

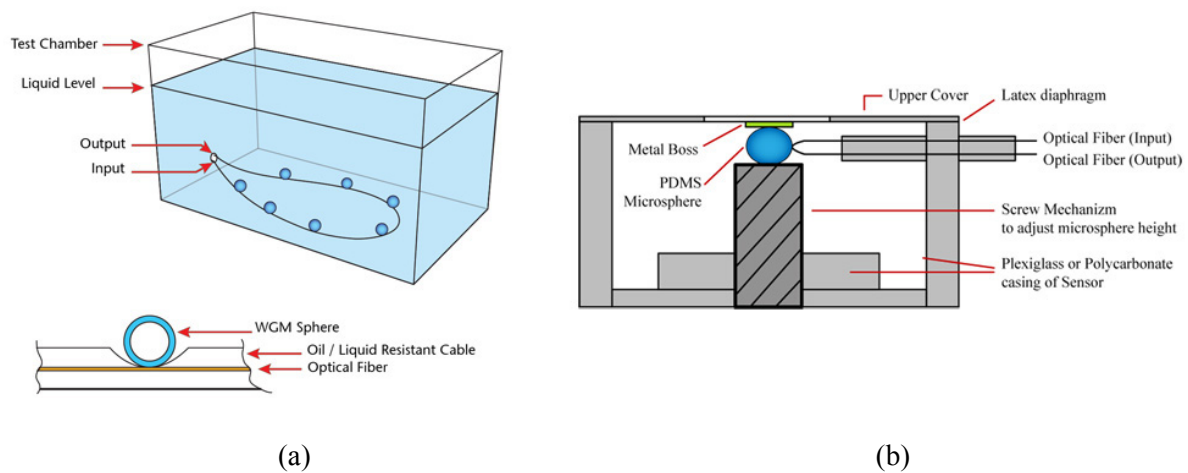
## **3. Whispering Gallery Mode Phenomenon**

### **3.1. Sensor and Experimental Design**

In collaboration with the Southern Methodist University Mechanical Engineering Faculty's Micro Sensors Lab. a totally new type of liquid level sensor is developed.

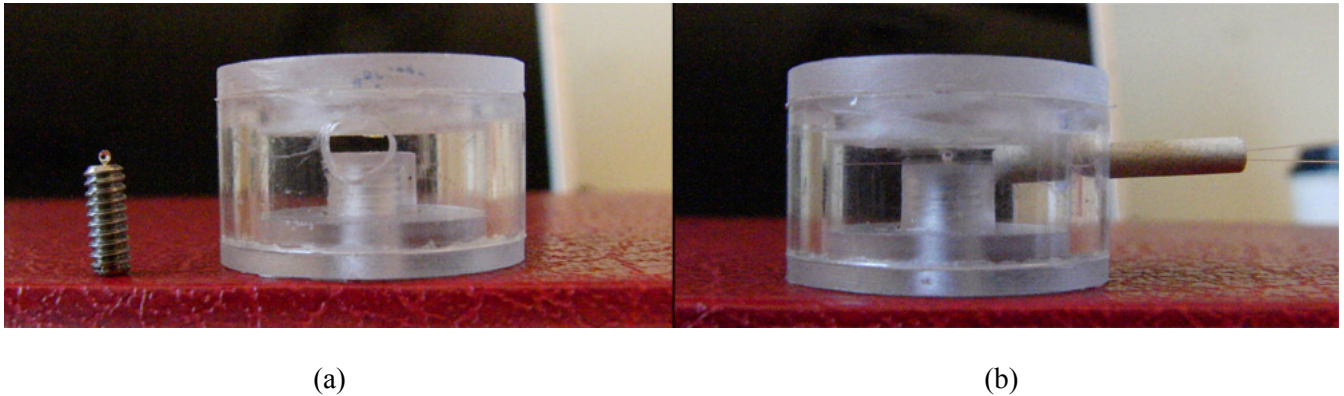
This new sensor is designed to detect pressure/force by using whispering gallery mode (WGM) phenomenon, and capable of working nearly in everywhere including underwater.

The target is to develop sensor prototypes using the existing WGM theory. The experimental design includes equipment such as; laser as the signal source, micro sphere as the sensing element, fiber optics, and a liquid container as the test medium (Fig. 1).



**Fig. 1.** Experimental setup of liquid level sensor using WGM method (a), WGM sensor (b).

WGM sensor should be resistant to fluids therefore a latex type membrane is used in the experiments. Fig. 2 shows detailed proposal of how to encapsulate the WGM sphere to make the sensor resistant to the medium including liquids.

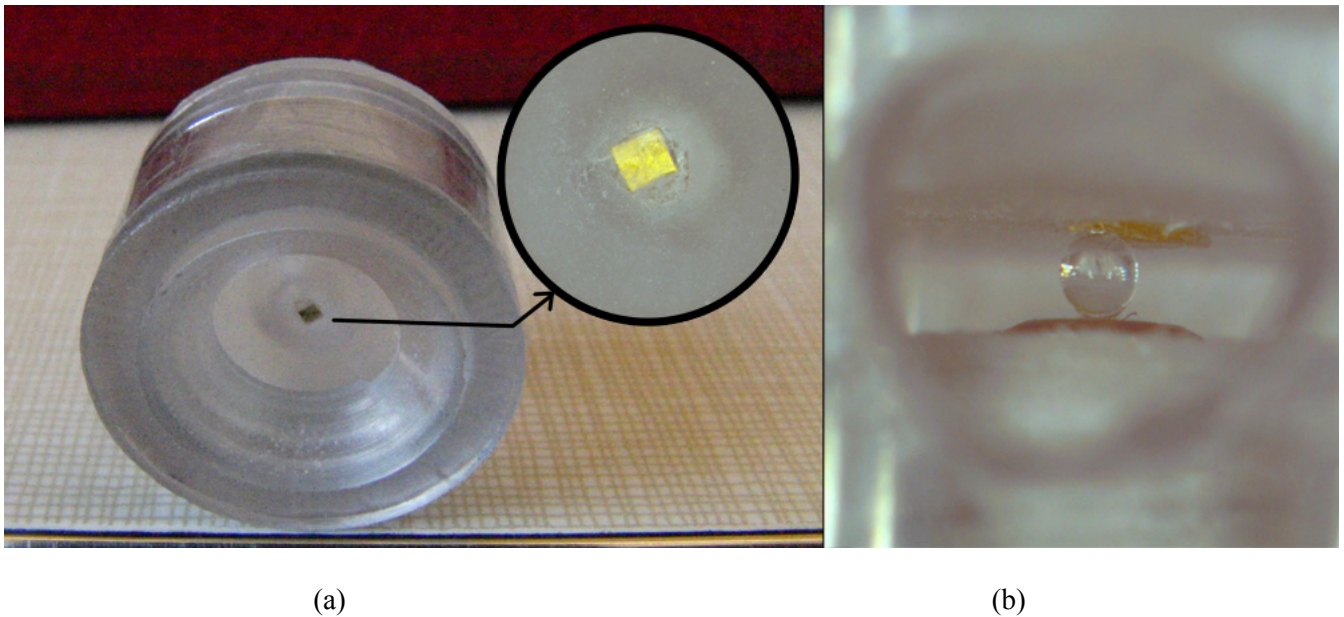


**Fig. 2.** Screw mechanism (a); Optical fiber placed in sensor (b).

To obtain traceable WGM shifts, first the fiber is tapered to very small diameters, and then touches the tapered fiber's core to the exact center of a PDMS sphere by using many translational stages. When the correct location of the fibers by is assessed using optical devices, the resonances are observed clearly by using the in house developed software. After observing the WGM resonances, the locations of the fiber ends are kept stable in the sensor by using adhesives. After completing this step, the sensor can be re-placed into its exact measurement location.

When building the sensor, a metal boss of size  $1 \times 1$ mm was also added inside the membrane, by having metal surfaces in both ends of the sphere. After adding the metal boss, PDMS sphere is placed between two metal surfaces, where the upper boss surface exerts the pressure to the sphere, while the bottom screw stays stable.

There is a screw mechanism to place and tune the location of the PDMS sphere in its correct position to touch the metal boss above. Metal boss (Fig. 3.) of size 1x1mm is assembled on the diaphragm, and directly applies the pressure on the sphere.



**Fig. 3.** Metal boss added to the latex membrane for greater sensitivity (a); The microsphere touching metal boss (b).

### 3.2. Theory and Equations

In the whispering gallery mode theory, light undergoes total internal reflection, and because it is trapped inside the sphere, WGMs are observed under certain conditions.

The details of the theory, the changes in WGM spheres applied force is as follows [7]:

$$2\pi n_0 a = l \lambda, \quad (1)$$

where,  $\lambda$  is the vacuum wavelength of laser,  $n_0$  is the refractive index,  $a$  is the radius of the sphere,  $l$  is the integer indicating the circumferential mode number.

A minute change in the size or the refractive index of the microsphere will lead to a shift in the resonance wavelength as:

$$\frac{d\lambda}{\lambda} = \frac{dn_0}{n_0} + \frac{da}{a}. \quad (2)$$

When a solid dielectric sphere of radius that is compressed by two pads made of high stiffness material, the applied force  $F$  will lead to a mechanical stress field inside the microsphere. It will also deform the sphere (strain), leading to a WGM shift. The deformation of the sphere can be obtained by solving the Navier equation [7]:

$$\nabla^2 \mathbf{u} + \frac{1}{1-2\nu} \nabla \nabla \cdot \mathbf{u} = 0, \quad (3)$$

where,  $u$  is the displacement of a given point within the sphere and  $\nu$  is the Poisson ratio.

For a symmetric loading, the expression is:

$$u_r = \sum_n [A_n(n+1)(n-2+4\nu)r^{n+1} + B_n nr^{n-1}]P_n(\cos \vartheta), \quad (4)$$

$r$  radial coordinate,  $\vartheta$  polar coordinate,  $u_r$  radial component of displacement,  $P_n$  Legendre polynomial,  $A_n - B_n$  constants determined by the boundary condition at the sphere surface.

For an elastic body along with the stress-displacement relationship, the stress distributions within the sphere are obtained as:

$$\begin{aligned} \sigma_{rr} &= 2G \sum [A_n(n+1)(n^2 - n - 2 - 2\nu)r^n + B_n n(n-1)r^{n-2}]P_n(\cos \vartheta), & \sigma_{rr} &= 2G \sum [A_n(n+1)(n^2 - n - 2 - 2\nu)r^n + B_n n(n-1)r^{n-2}]P_n(\cos \vartheta), \\ \sigma_{\varphi\varphi} &= 2G \sum \left\{ [A_n(n+1)(n-2-2\nu-4n\nu)r^n + B_n nr^{n-2}]P_n(\cos \vartheta) + [A_n(n+5-4\nu)r^n + B_n r^{n-2}] \cot \vartheta \frac{dP_n(\cos \vartheta)}{d\vartheta} \right\}, & \sigma_{r\vartheta} &= 2G \sum [A_n(n^2 + 2n - 1 + 2\nu)r^n + B_n(n-1)r^{n-2}] \frac{dP_n(\cos \vartheta)}{d\vartheta}. \end{aligned} \quad (5)$$

$G$ = shear modulus of the sphere material.

Neglecting the friction at the contact point between the sphere and the plates, the boundary conditions are

$$\begin{aligned} \sigma_{rr}(a) &= \begin{cases} -p(\vartheta), & 0 \leq \vartheta \leq \vartheta_0 \quad \text{and} \quad \pi - \vartheta_0 \leq \vartheta \leq \pi \\ 0, & \vartheta_0 \leq \vartheta \leq \pi - \vartheta_0, \end{cases} \\ \sigma_{r\vartheta}(a) &= 0 \quad 0 \leq \vartheta \leq \pi, \end{aligned} \quad (6)$$

where angle  $\vartheta_0$  defines the extent of the contact between the plate and the sphere. The pressure  $p$  exerted by plates of infinite stiffness on the sphere is given by

$$p(\vartheta) = \frac{3F}{2\pi a_0^3} \sqrt{a_0^2 - a^2 \sin^2(\vartheta)}, \quad (7)$$

$a_0$  = the radius of contact area, as shown in Fig. 1 (b).

In order to obtain coefficients  $A_n$  and  $B_n$  in Eqs. (4) and (5), the boundary condition given in Eq. (6) has to be expanded in terms of the Legendre polynomial in the following form:

$$\sigma_{rr}(a) = \sum_n H_n P_n(\cos \vartheta). \quad (8)$$

Then the coefficient  $H_n$  is obtained as

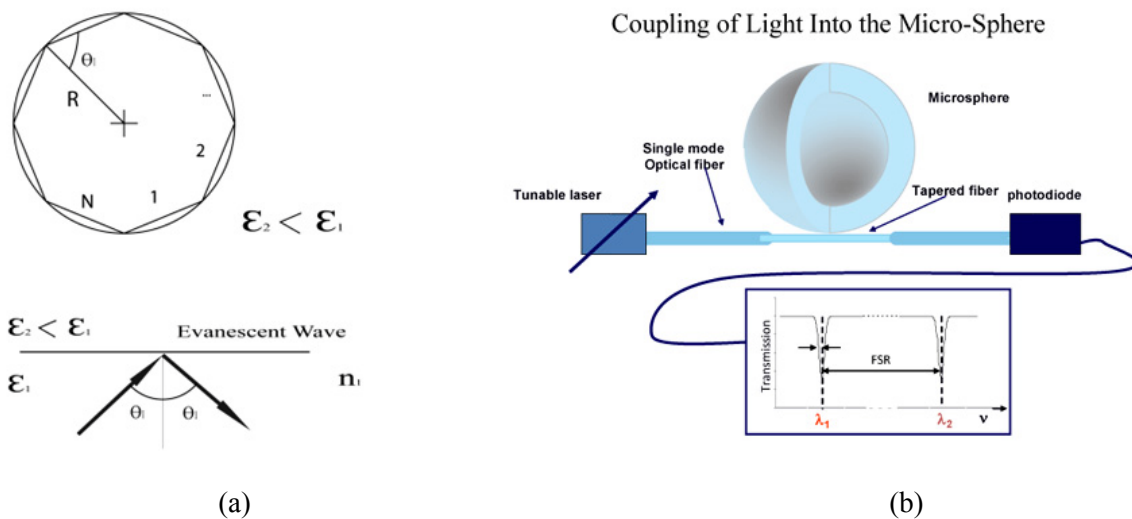
$$H_n = (2n + 1) \times \int_0^{\pi/2} P_n(\cos \vartheta) \frac{3F}{2\pi a_0^3} \sqrt{a_0^3 - a^2 \sin^2(\vartheta)} \sin \vartheta d\vartheta \quad (9)$$

By satisfying the boundary condition, Eq. (6), for Eqs. (5) and (8), coefficients  $A_n$  and  $B_n$  are obtained as follows:

$$A_n = \frac{H_n}{2Ga^n[(n+1)(n^2 - n - 2 - 2\nu) - n(n^2 + 2n - 1 + 2\nu)]}$$

$$B_n = -\frac{H_n}{2G[(n+1)(n^2 - n - 2 - 2\nu) - n(n^2 + 2n - 1 + 2\nu)]} \times \frac{(n^2 + 2n - 1 + 2\nu)a^{2-n}}{(n-1)} \quad (10)$$

When we look at Fig. 4, it can be seen that each time the light bounces off the inner surface of the sphere due to total internal reflection, the reflected wave experiences a “phase delay”,  $\phi$ . This phase delay is a function of the light wavelength,  $\lambda$ ; and incidence angle; as well as the sphere-to surrounding refraction index ratio,  $n_1/n_2$ .

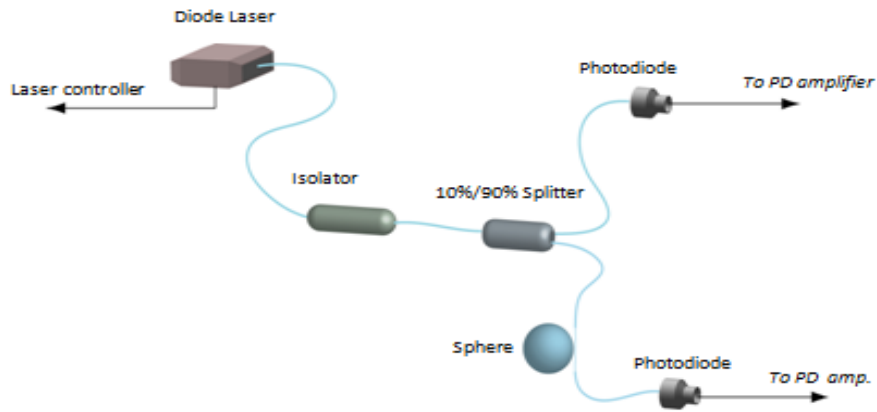


**Fig. 4.** Total internal reflections of the sensor (a); WGM Shifts (b).

As it can be seen easily, the laser light comes into the microsphere in its contact point in the tapered film, and the light undergoes total internal reflections in the sphere, which causes the phase shifts or in other words WGM shifts.

As illustrated in Fig. 5, while light starts re-circulating in the sphere a resonance shift occurs in the light when compared with the reference light beam.

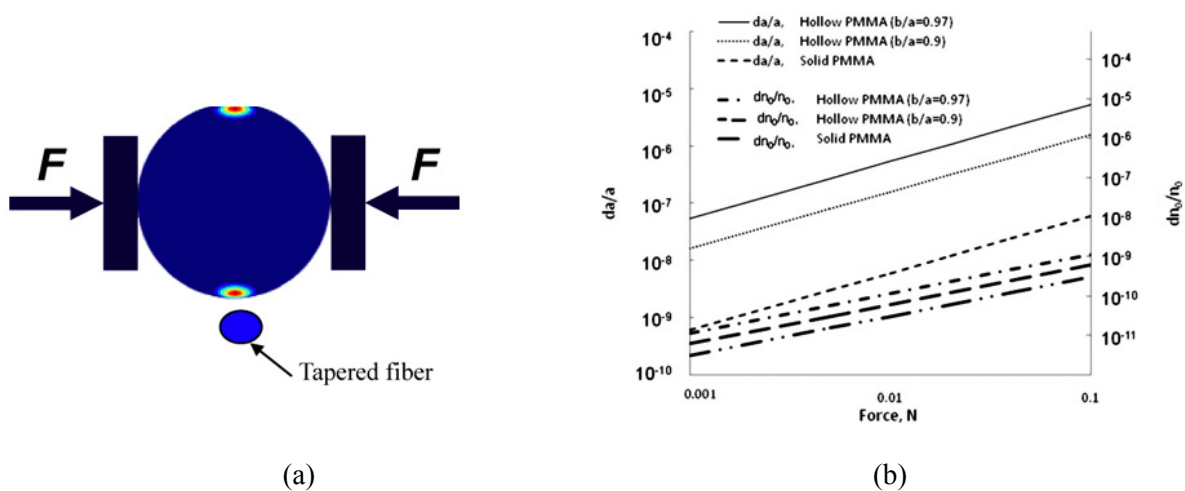
Fig. 5 presents the experiment setup in its general form. The light coming from the laser splits into two, leaving a small percentage for reference going directly to the photodiode, while keeping a high percentage (90 % in this scenario) for WGM shift, which goes directly to the microsphere. So after the WGM phase shift occurs, it has been noticed by checking the differences between the reference light and WGM part of it.



**Fig. 5.** The experiment setup [3].

The system is driven by a tunable distributed feedback laser (with 1.312  $\mu\text{m}$  central wavelength and 10 mW maximum power). The current is tuned over a range of  $\sim 0.1$  nm. The laser is coupled into a single mode optical fiber, whose output end is connected to a fast photodiode to monitor the transmission spectrum. A section of the fiber is tapered down to a diameter of  $\sim 10$   $\mu\text{m}$  (by heating and stretching the fiber). The microsphere is brought into contact with the tapered fiber section to facilitate light coupling between fiber and resonator. The transmission spectrum through the fiber is normalized by a reference signal taken directly from the laser. The transmission spectrum is digitized using a 16 bit analog to digital converter and the WGM positions are determined using an in-house software. A personal computer controls both the frequency tuning of the laser and the data acquisition [7].

When force is applied to the resonator, a change occurs in both the shape and index of refraction of the resonator (Fig. 6). The formulas below demonstrate that we can measure the force by detecting the changes occurred in the shape and the index of refraction [4].



**Fig. 6.** Force is applied to the resonator (a); Force shifts the resonance(b).

Fig. 6 above shows that, the force shifts the resonance, but more importantly according to different materials, resonance shift also differs.

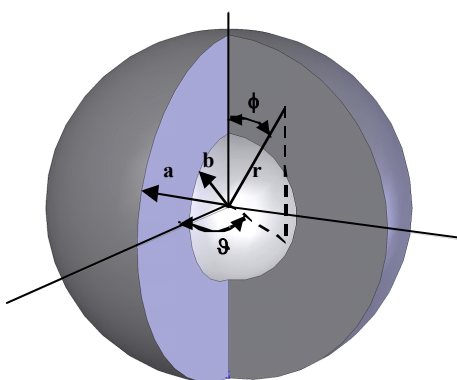
For the solid microsphere, the last term in Eq. (2) can be calculated by evaluating Eq. (4) at  $r=a$  and then dividing it by the sphere radius  $a$ :

$$\frac{da}{a} = \sum_n \frac{H_n}{4G(n^2 + 2n\nu + n + \nu + 1)} \times \left[ \frac{2 - 4n^2 + \nu(4n^2 - 2n - 4)}{n - 1} \right] P_n(0) \quad (11)$$

Next the effect of stress on refractive index perturbation,  $dn_0/n_0$ , in Eq. (2) is determined.

Using the coordinate system illustrated in Fig. 7, Neumann–Maxwell equations provide the relationship between stress and refractive index as follows:

$$\begin{aligned} n_r &= n_{0r} + C_1 \sigma_{rr} + C_2 (\sigma_{\vartheta\vartheta} + \sigma_{\phi\phi}) \\ n_{\vartheta} &= n_{0\vartheta} + C_1 \sigma_{\vartheta\vartheta} + C_2 (\sigma_{rr} + \sigma_{\phi\phi}) \\ n_{\phi} &= n_{0\phi} + C_1 \sigma_{\phi\phi} + C_2 (\sigma_{\vartheta\vartheta} + \sigma_{rr}) \end{aligned} \quad (12)$$



**Fig. 7.** Coordinate system used in the stress and strain formulation of a sphere.

Here  $n_r$ ,  $n_{\vartheta}$ ,  $n_{\phi}$  are the refractive indices in the direction of the three principle stresses and  $n_{0r}$ ,  $n_{0\vartheta}$ ,  $n_{0\phi}$  are those values for the unstressed material. Coefficients  $C_1$  and  $C_2$  are the elasto-optical constants of the material, and for both PMMA and PDMS,  $C_1=C_2$ . For PMMA  $C_1=C_2=C=-10^{-10} \text{ m}^2/\text{N}$  and for PDMS this value is  $C_1=C_2=C=-1.75 \times 10^{-10} \text{ m}^2/\text{N}$ . Thus, for a spherical sensor, the fractional change in the refractive index due to mechanical stress is reduced to

$$\begin{aligned} \frac{dn_0}{n_0} &= \frac{n_r - n_{0r}}{n_{0r}} = \frac{n_{\vartheta} - n_{0\vartheta}}{n_{0\vartheta}} = \frac{n_r - n_{0\phi}}{n_{0\phi}} \\ &= \frac{C(\sigma_{rr} + \sigma_{\vartheta\vartheta} + \sigma_{\phi\phi})}{n} \end{aligned} \quad (13)$$

In the present WGM optical sensor, light is traveling in a plane that is normal to the applied force. Thus, evaluating the appropriate expressions for stress in Eq. (5) at  $\vartheta=\pi/2$  and  $r=a$ , and introducing them into Eq. (13), the relative change in the refractive index due to force  $F$  is obtained as

$$\frac{dn_0}{n_0} = \frac{C}{2n_0} \sum_n \left[ \frac{H_n(n+1)(n^2 + 3n + 4 + 4\nu + 4\nu n)}{(n^2 + 2\nu n + n + \nu + 1)} \right] P_n(0). \quad (14)$$

Equations (11) and (14) represent the effect of strain and stress, respectively, on the WGM shift of the solid dielectric sphere. Plugging these into Eq. (2), we obtain the total WGM shift as

$$\frac{d\lambda}{\lambda} = \sum_n \frac{H_n}{2(n^2 + 2n\nu + n + \nu + 1)} \times \left[ \frac{2 - 4n^2 + \nu(4n^2 - 2n - 4)}{(n-1)2G} + \frac{C(n+1)(n^2 + 3n + 4 + 4\nu + 4\nu n)}{n_0} \right] P_n(0). \quad (15)$$

### 3.3. PDMS Sensor

Polydimethylsiloxane (PDMS) belongs to a group of polymeric organosilicon compounds that are commonly referred to as silicones [7].

PDMS is an elastomer that is a mixture of two components: a base and a curing agent. By changing the ratio between the base and the curing agent, it is possible to obtain elastic materials with Young's modulus ranging between 3 and 1000 kPa (corresponding to a base-to-curing agent volume ratio of 60:1 and 10:1, respectively) [7].

The Young modulus of a PDMS microsphere is substantially smaller than that of PMMA sphere of the same diameter resulting in comparable sphere deformations at much smaller force levels. Thus, determining the sensitivity of the PDMS force sensors is a more challenging task; the load-cell based measurement setup would not provide sufficient resolution for sensor calibration. Moreover, since the force levels in these calibrations are ( $<10^{-6}$  N), even the aerodynamic forces due to air currents (air drafts and natural convection) would have considerable adverse effect. To avoid such problems, the setup shown in Fig. 5 has been built and kept enclosed in a vacuum chamber, as shown in the figure.

In order to account for the sphere deformation, a Hertz-contact analysis was carried out on the spheres for a range of force values. Using this force versus deformation data and modeling the sphere as a linear spring system, the equivalent spring constant  $k_{\text{sphere}}$  was determined for each sphere size and PDMS mixture ratio used in the experiments. Then, the equivalent spring constant of the beam-sphere system was determined as: [4]

$$\frac{1}{k_e} = \frac{1}{k_{\text{sphere}}} + \frac{1}{k_{\text{beam}}}, \quad (16)$$

where the spring constant for the beam is

$$k_{\text{beam}} = \frac{3E \pi D^4}{64L^3}. \quad (17)$$

Here, E is the Young modulus, D is the diameter, and L is the length of the silica beam. The force exerted on the sphere is then calculated as

$$F = k_e \delta, \quad (18)$$

where  $\delta$  is the displacement of the translation stage and is determined by the Michaelson interferometer signal as

$$\delta = l \frac{\lambda_m}{2}. \quad (19)$$

Here,  $l$  is an integer and  $\lambda_m$  is the wavelength of the He–Ne, laser (632.8 nm).

The WGM shift dependence on the applied force for a solid PDMS microsphere of 910  $\mu\text{m}$  diameter with base-to-curing agent volume ratio of 50:1 ( $E = 10 \text{ kPa}$ ). The figure indicates a strong agreement between the experiments and Eq. (15).

### 3.4. Sensor Bandwidth

Sensor bandwidth is an important variable in most force measurements. We take the frequency at the first peak of the frequency response of the sensor as the first natural frequency of the sphere. In this approach, the other moving parts of the sensor are not taken into account and the sphere is considered undamped. It should be noted that the additional mass of the other moving parts will reduce the bandwidth estimate. We calculate the resonant frequency by numerically solving the characteristic equation for the sphere.

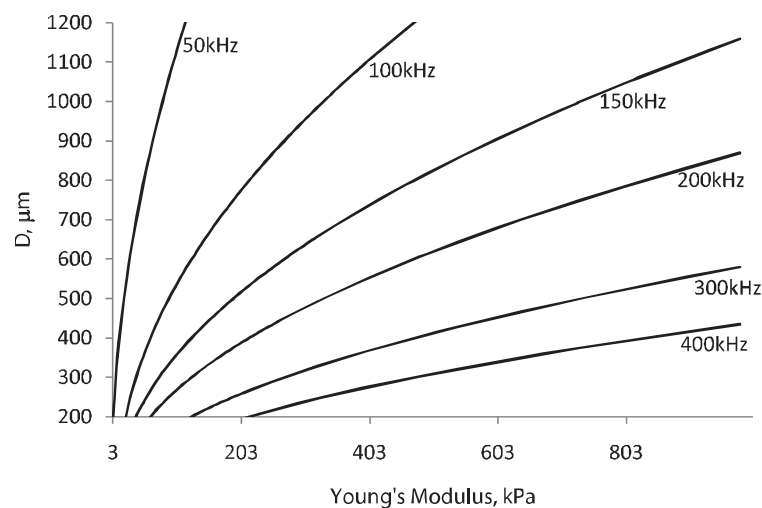
$$\frac{1-\nu}{1-2\nu} \left[ 2 \left( a \frac{\omega_n}{C^*} \right) J_{1/2} \left( a \frac{\omega_n}{C^*} \right) - 2 \left( a \frac{\omega_n}{C^*} \right) J_{3/2} \left( a \frac{\omega_n}{C^*} \right) \right] = 0, \quad (20)$$

where  $\omega_n$  is the angular frequency,  $J_n$ 's are the Bessel functions of first kind, and  $C^*$  is the compressive wave velocity defined as

$$C^* = \sqrt{\frac{\lambda + 2\mu}{\rho}}, \quad (21)$$

Where  $\lambda$  and  $\mu$  are the Lamé constants and  $\rho$  is the microsphere material density.

As shown in Fig. 8, the sensor bandwidth is significantly smaller for sphere sensors with low Young's moduli than those with the higher values. For a given  $E$ , the smaller the sensor, the larger the bandwidth due to the effect of sensor mass.



**Fig. 8.** Estimated sensor bandwidths for solid PDMS spheres.

Analytical studies of polymeric spheres under the effect of uniaxial compressive force have been carried out and the analysis has been validated through experiments. The results show that the force

sensitivity for a WGM sensor is a function of the sphere material property and geometry. A wide range of sensitivities can be obtained by choosing different combinations of sphere material and geometry.

While the sensitivity can be improved by choosing a material with lower Young's modulus, there is a tradeoff in performance. For solid polymeric microspheres, the bandwidth of the sensor becomes smaller as the sensitivity increases.

For PDMS microsphere sensors, the analysis indicates that thin walled hollow PDMS sensors have both higher force resolutions and larger bandwidths than their solid counterparts, making them highly attractive in sensor applications. But in our case, a solid sphere is enough to measure the liquid depths, even more sensitive than its current competitors.

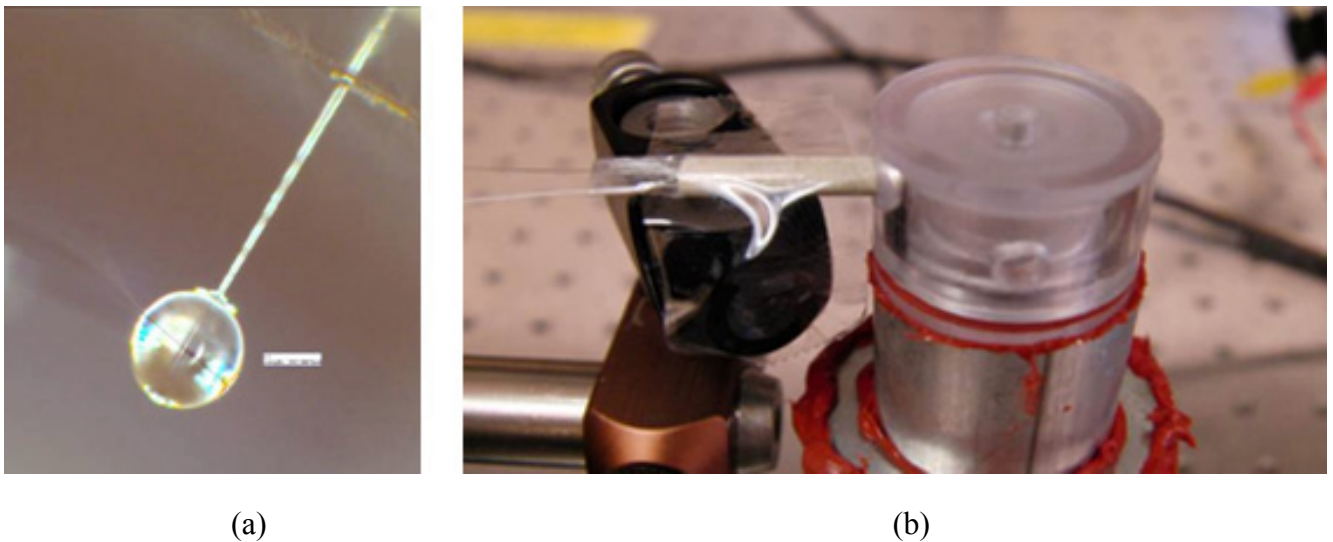
## 4. Experimental Results

### 4.1. Experimental Design

Using the above summarized approach; WGM shifts may be calculated according to the pressure changes of the medium, or in other words the external pressure changes.

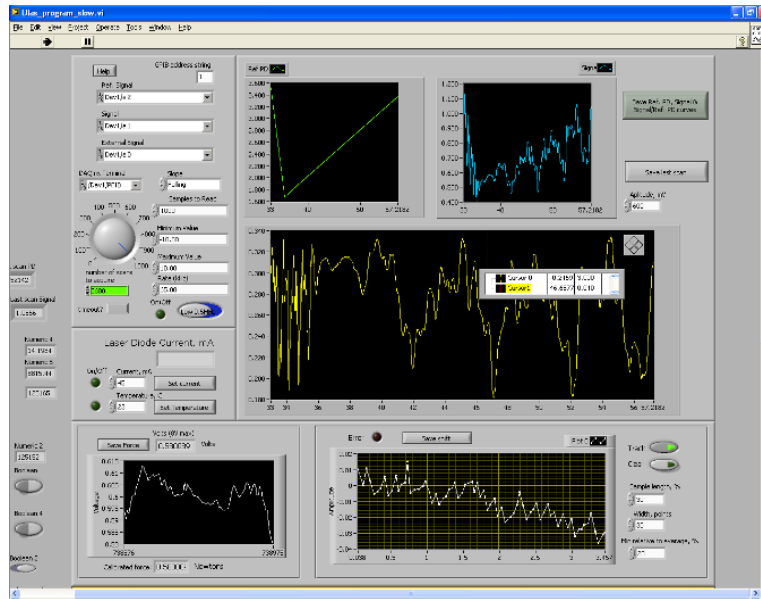
For this aim, the most suitable experiment set up has been built to measure the pressure changes of the medium, which is related with the height of the liquid.

Sensor is produced in SMU's Micro Sensor Laboratories by the aid of manufacturing facilities. Then glassfiber has been thinned by using fire torch, to make it thinner enough to interact the core of the fiber with the sphere. After the tapering stage, by using different translational stages, fiber core touched to sphere's mid-point to turn the theory into reality (Fig. 9).



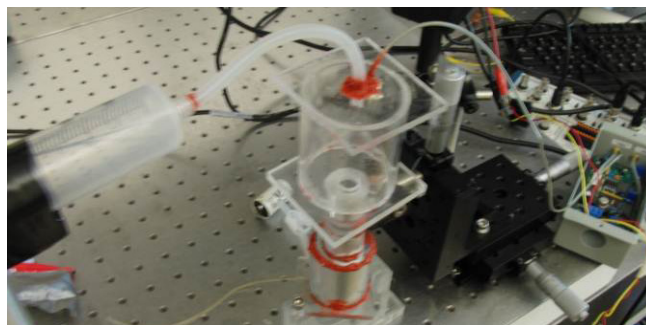
**Fig. 9.** A typical PDMS sphere (a); sensor (b).

When the fiber core transfers the light to the sphere, light undergoes total internal reflections, and because it is trapped inside the sphere, where the WGM shifts are observed as shown in Fig. 10, which shows the WGM shifts are tracked and recorded by special software.



**Fig. 10.** The snap-shot of the software screen.

The air pressure experiments have been performed by applying pressure to a cylinder assembled on top of the sensor, by using a syringe (Fig. 11). A reference pressure signal is measured by a pipe which is connected to pressure transducer.



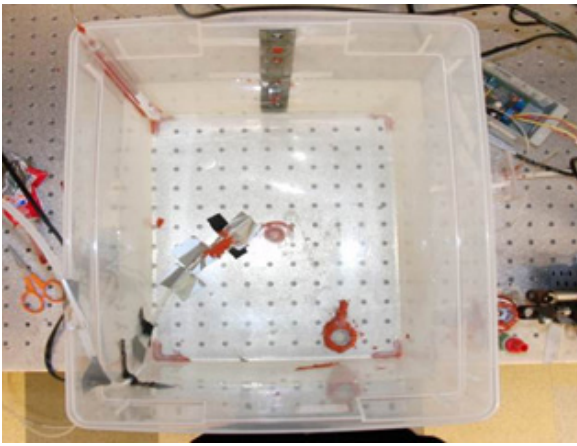
**Fig. 11.** The air pressure experiment.

Water pressure/depth experiments have been more complex. A u tube, again sealed and connected to the pressure transducer, as well as a mm scale added for calibrating the pressure transducer and changing the pressure values into mm water height.

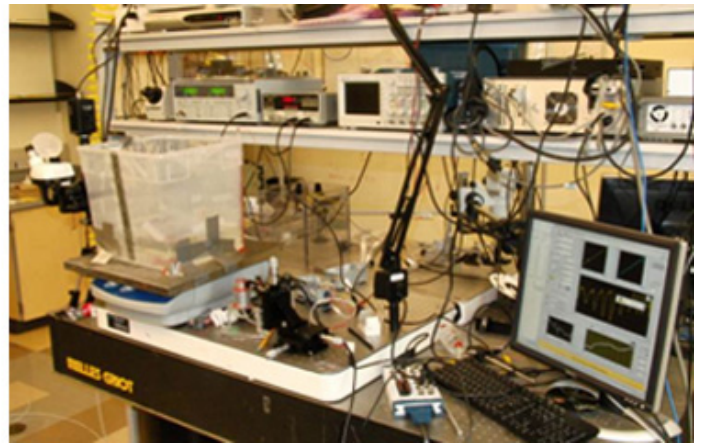
General experiment setup can be seen in Fig. 12(b). For draining and adding water a pipe added to the container.

Two sensors were also put together, but the software was not able to track WGM shifts of two sensors at the same time.

For the industrial usage, serial production sensors with better quality products and finishes should be used according to the application requirements.



(a)

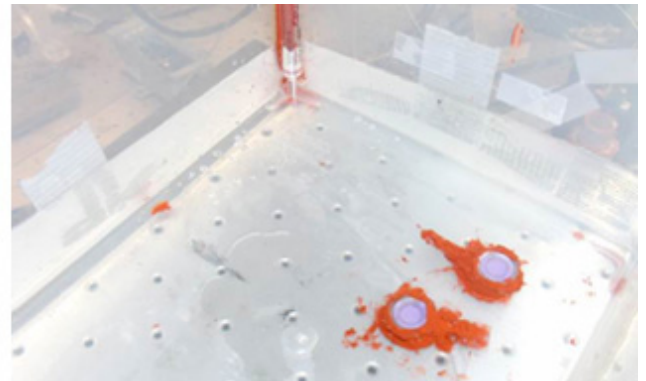


(b)

**Fig. 12.** Water pressure/depth experiments(a); General experiment setup (b).



(a)



(b)

**Fig. 13.** Two sensors in container (a); The sensors have covered with high temperature resistant silicon for water sealing (b).

#### **4.1. Experimental Data**

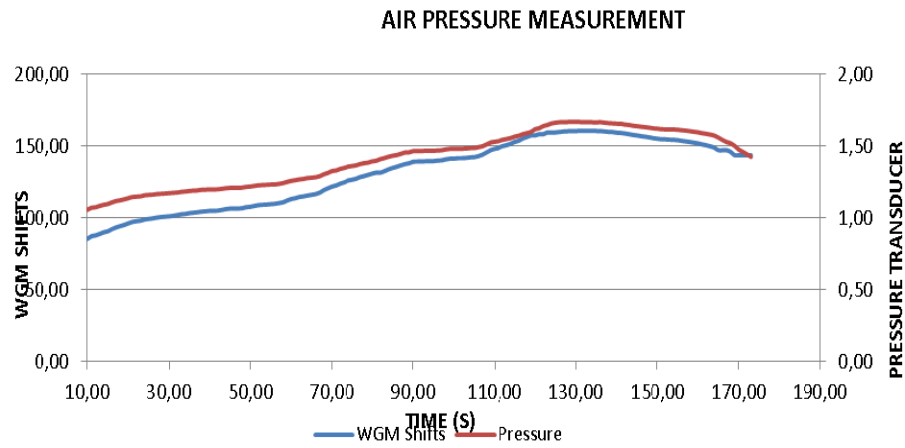
As expressed in the previous section, the initial experiments have been performed by first changing the air pressure, and then changing the liquid depths.

The recovered data is reviewed according to the experimental order.

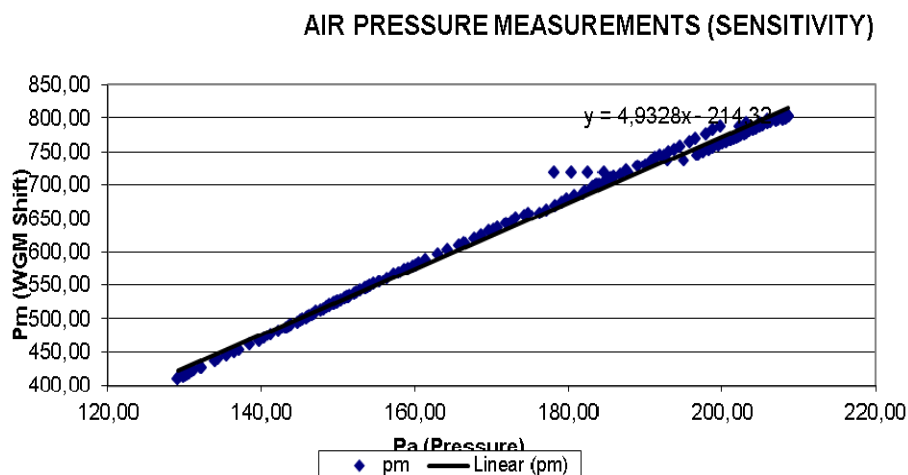
Fig. 14 (b) shows the sensitivity of the sensor in air pressure measurements. Y axis represents the resonance shifts in Pm, while X axis represents the pressure changes in Pa.

The red line represents the pressure transducer, while the blue line represents the WGM resonance shifts in miliamperes.

According to the data above, the sensitivity of the sensor is around 4-5 Pm/Pa.



(a)



(b)

**Fig. 14.** Air pressure measurements (a); The sensitivity of the sensor in air pressure measurements (b).

When we use the sensitivity formulas:

$$dF = \frac{1}{Q} \cdot \frac{\lambda}{S},$$

where Q is the Quality factor, S is the sensitivity of the sensor,  $dF$  is the minimum force difference that can be used, and  $\lambda$  is the laser's wavelength.

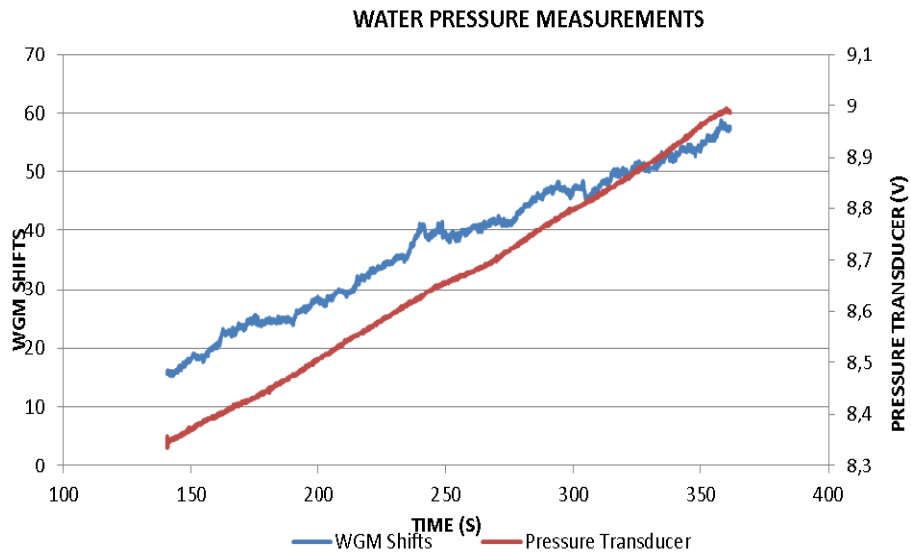
Therefore, in our case, the minimum force/pressure that can be detected is:

$$dF = \frac{1}{10^7} \cdot \frac{1,310 \cdot 10^6 \text{ pm}}{4,9238 \frac{\text{pm}}{\text{Pa}}} \cong 0,0266 \text{ Pa}$$

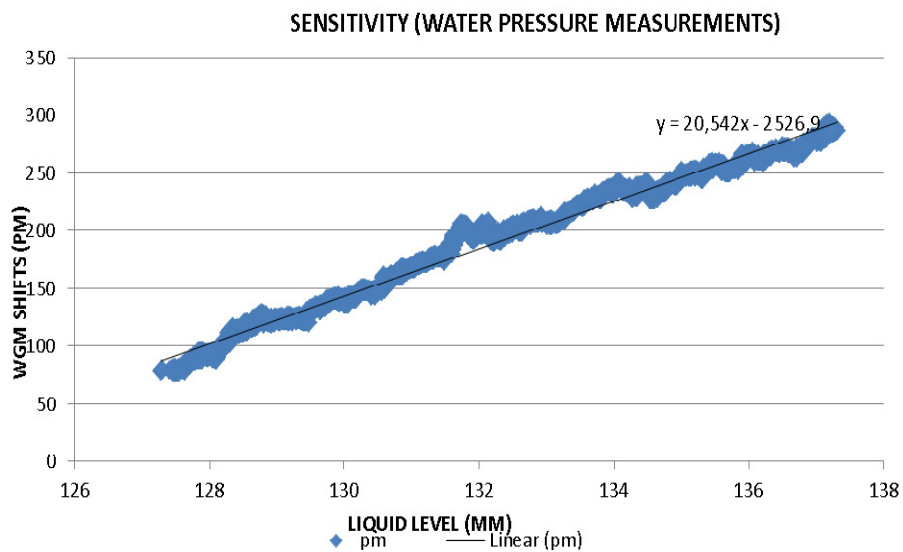
which is a very precise value.

Fig. 15(a) shows the water pressure measurements. The red line represents the pressure transducer, while the blue line represents the WGM resonance shifts in mA.

Fig. 15 (b) shows the sensitivity of the sensor in water pressure measurements during adding water. Y axis represents the resonance shifts in Pm, while X axis represents the pressure changes in Pa.



(a)



(b)

**Fig. 15.** Water pressure measurements (a); sensitivity of the sensor in water pressure measurements during adding water (b).

For reliability of the results, the pressure transducer was calibrated for each measurement either when filling or draining water.

Fig. 17 (a) shows the water pressure measurements during draining water. The red line represents the pressure transducer, while the blue line represents the WGM resonance shifts in miliamperes.

Fig. 17 (b) shows the sensitivity of the sensor under water while draining water. Y axis represents the resonance shifts in Pm, while X axis represents the pressure changes in Pa.

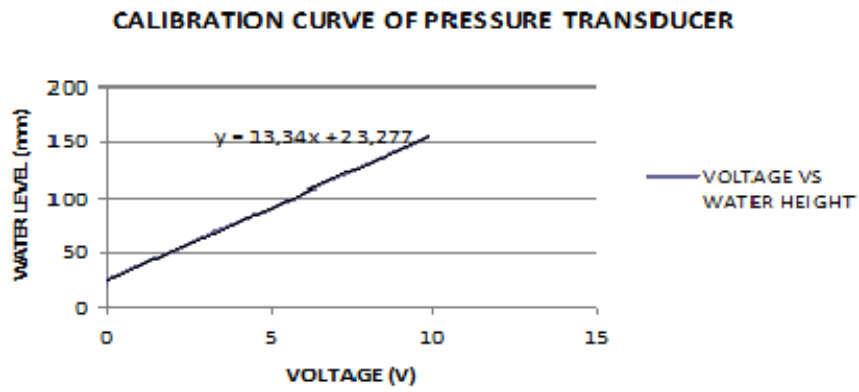
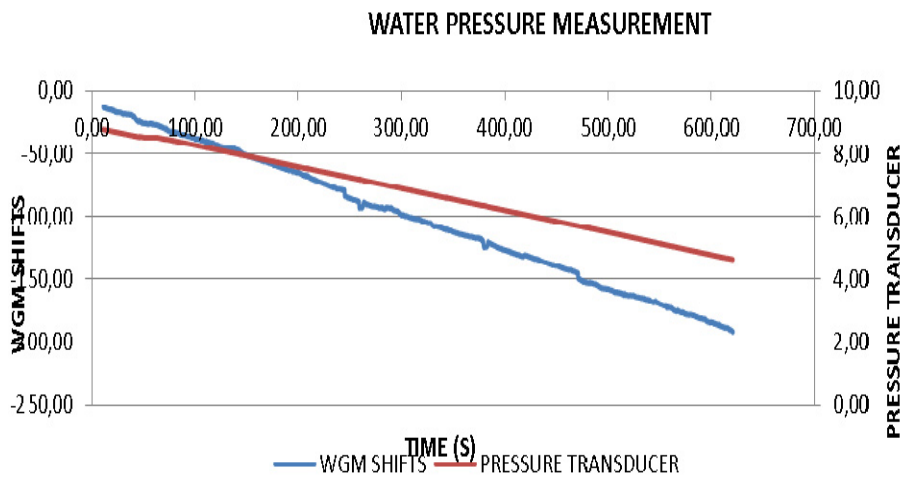
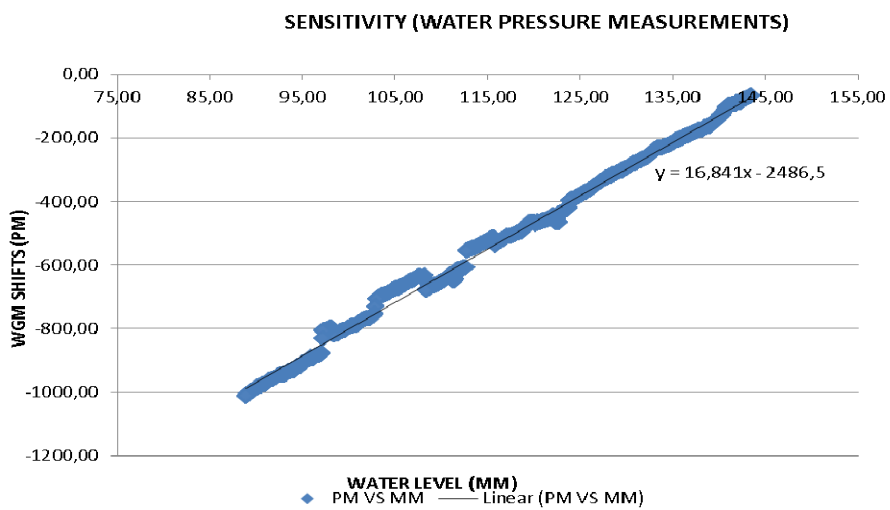


Fig. 16. Calibration of the transducer.



(a)



(b)

Fig. 17. Water pressure measurements during draining water (a); the sensitivity of the sensor under water while draining water (b).

When we use the sensitivity formulas for liquid level measurements:

$$dF = \frac{1}{Q} \cdot \frac{\lambda}{S}$$

So in our case, it can be the minimum force/pressure that can be measured is:

$$\begin{aligned} dF_{\text{Filling}} &= \frac{1}{10^7} \cdot \frac{1,310 \cdot 10^6 \text{ pm}}{20,542 \frac{\text{pm}}{\text{mmH}_2\text{O}}} \\ &\cong 0,00637 \text{ mmH}_2\text{O} = 0,0637 \text{ Pa} \\ dF_{\text{Draining}} &= \frac{1}{10^7} \cdot \frac{1,310 \cdot 10^6 \text{ pm}}{16,841 \frac{\text{pm}}{\text{mmH}_2\text{O}}} \\ &= 0,0077 \text{ mmH}_2\text{O} = 0,077 \text{ Pa} \end{aligned}$$

which is also a very precise value for sensing the liquid levels.

## 5. Conclusions

According to the results, it can be said that, we have a new WGM pressure sensor which has 4 Pm/Pa sensitivity in air pressure applications, so it is sensitive to measure 0.0266 Pa.

The sensors also have a sensitivity around 20 Pm/mmH<sub>2</sub>O in water measurements, which is equal to the sensitivity of 0.0064 mm of water height differences, which is also a lot more sensitive than the current competitor devices capable of measuring  $\pm 2$  mm of water height differences. Also because of its optical principle can be worked in any environment without being affected by the availability of flammable liquids and gasses etc. it is a sensor that has a wide range of applications, therefore it is definitely a better sensor to be used in many different areas all around the globe.

## Acknowledgements

Authors would like to thank to Prof. Volkan Otugen, Chair of Mechanical Engineering department and director of Micro-sensors laboratory of SMU, for his valuable contributions, and hosting the experiments in Micro Sensors lab. of Southern Methodist University; Ulas Ayaz (M.Sc.) for his valuable cooperation and contribution, and the manager of manufacturing facilities in SMU, Necdet Yildirim for his advices and helps during the sensor development stages.


## References

- [1]. M. E. Erdem, D. Gunes, Liquid Level Sensor in Automotive Design, in *Proceedings of the 5<sup>th</sup> International Conference on Sensor Technologies and Applications (SENSORCOMM '2011)*, pp. 166-171.
- [2]. Level Sensor: [http://en.wikipedia.org/wiki/Level\\_sensor](http://en.wikipedia.org/wiki/Level_sensor) (15.02.2011).
- [3]. T. Ioppolo, U. K. Ayaz, and M. V. Ötügen, High Resolution Force Sensor Based on Morphology Dependent Optical Resonators Polymeric Spheres, *J. Appl. Physics*, Vol. 105, 2009, p. 013535.
- [4]. Ioppolo, T., and Otugen, M. V., Pressure Tuning of Whispering Gallery Mode Resonators, *J. Opt. Soc. Am. B*, Vol. 24, No. 10, 2007, pp. 2721–2726.
- [5]. D. D. Hongerholt, Greg A. Seidel, Charles G. HUss, and Eric D. Haugen, Ultrasonic technology for nonintrusive level measurement on commercial aircraft, *AIP Conference Proc.* Vol. 557, April 30, 2001, pp. 1787-1794.
- [6]. P. Nath, P. Datta, and K. Ch Sarma, All fiber-optic sensor for liquid level measurement, *Microwave and*

*Optical Technology Letters*, Vol. 50, Issue 7, July 2008, pp. 1982-1984.

- [7]. T. Ioppolo, M. Kozhevnikov, V. Stepaniuk, M. V. Ötügen, and V. Sheverev, A micro-optical force sensor concept based on whispering gallery mode resonators, *Applied Optics*, Vol. 47, Issue 16, 2008, pp. 3009-3014.

2012 Copyright ©, International Frequency Sensor Association (IFSA). All rights reserved.  
(<http://www.sensorsportal.com>)



## Handbook of Laboratory Measurements and Instrumentation

Maria Teresa Restivo  
Fernando Gomes de Almeida  
Maria de Fátima Chouzal  
Joaquim Gabriel Mendes  
António Mendes Lopes

The Handbook of Laboratory Measurements and Instrumentation presents experimental and laboratory activities with an approach as close as possible to reality, even offering remote access to experiments, providing to the reader an excellent tool for learning laboratory techniques and methodologies. Book includes dozens videos, animations and simulations following each of chapters. It makes the title very valued and different from existing books on measurements and instrumentation.

**IFSA**  
International Frequency Sensor Association Publishing

Order online:  
[http://www.sensorsportal.com/HTML/BOOKSTORE/Handbook\\_of\\_Measurements.htm](http://www.sensorsportal.com/HTML/BOOKSTORE/Handbook_of_Measurements.htm)



## Universal Frequency-to-Digital Converter (UFDC-1 and UFDC-1M-16) in MLF (5 x 5 x 1 mm) package

# SMALL WORLD - BIG FEATURES

SWP, Inc., Toronto, Ontario, Canada,  
Tel. + 34 696067716, fax: +34 93 4011989, e-mail: [sales@sensorsportal.com](mailto:sales@sensorsportal.com)  
[http://www.sensorsportal.com/HTML/E-SHOP/PRODUCTS\\_4/UFDC\\_1.htm](http://www.sensorsportal.com/HTML/E-SHOP/PRODUCTS_4/UFDC_1.htm)

## Guide for Contributors

---

### Aims and Scope

*Sensors & Transducers Journal* (ISSN 1726-5479) provides an advanced forum for the science and technology of physical, chemical sensors and biosensors. It publishes state-of-the-art reviews, regular research and application specific papers, short notes, letters to Editor and sensors related books reviews as well as academic, practical and commercial information of interest to its readership. Because of it is a peer reviewed international journal, papers rapidly published in *Sensors & Transducers Journal* will receive a very high publicity. The journal is published monthly as twelve issues per year by International Frequency Sensor Association (IFSA). In addition, some special sponsored and conference issues published annually. *Sensors & Transducers Journal* is indexed and abstracted very quickly by Chemical Abstracts, IndexCopernicus Journals Master List, Open J-Gate, Google Scholar, etc. Since 2011 the journal is covered and indexed (including a Scopus, Embase, Engineering Village and Reaxys) in Elsevier products.

### Topics Covered

Contributions are invited on all aspects of research, development and application of the science and technology of sensors, transducers and sensor instrumentations. Topics include, but are not restricted to:

- Physical, chemical and biosensors;
- Digital, frequency, period, duty-cycle, time interval, PWM, pulse number output sensors and transducers;
- Theory, principles, effects, design, standardization and modeling;
- Smart sensors and systems;
- Sensor instrumentation;
- Virtual instruments;
- Sensors interfaces, buses and networks;
- Signal processing;
- Frequency (period, duty-cycle)-to-digital converters, ADC;
- Technologies and materials;
- Nanosensors;
- Microsystems;
- Applications.

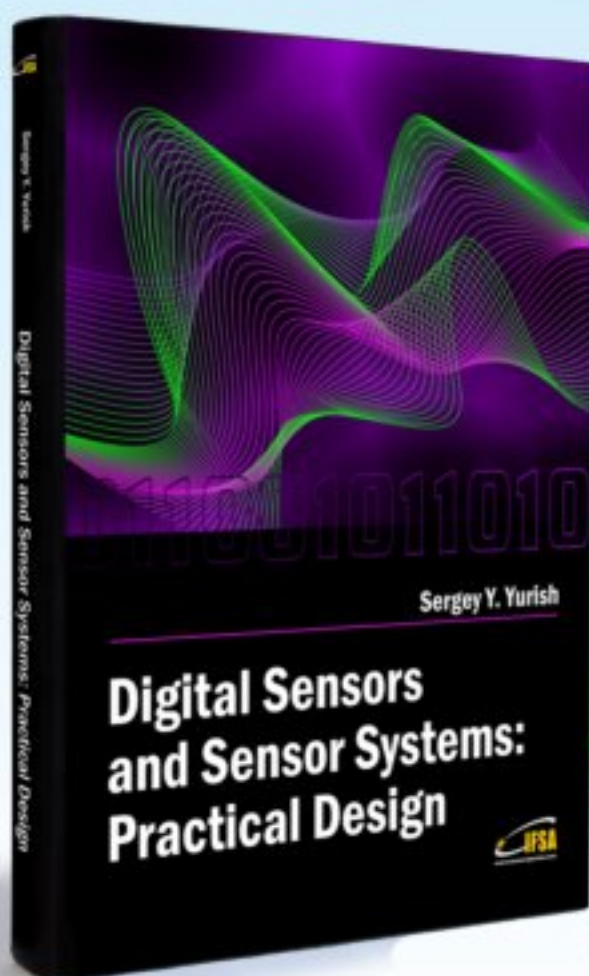
### Submission of papers

Articles should be written in English. Authors are invited to submit by e-mail [editor@sensorsportal.com](mailto:editor@sensorsportal.com) 8-14 pages article (including abstract, illustrations (color or grayscale), photos and references) in both: MS Word (doc) and Acrobat (pdf) formats. Detailed preparation instructions, paper example and template of manuscript are available from the journal's webpage: <http://www.sensorsportal.com/HTML/DIGEST/Submission.htm> Authors must follow the instructions strictly when submitting their manuscripts.

### Advertising Information

Advertising orders and enquires may be sent to [sales@sensorsportal.com](mailto:sales@sensorsportal.com) Please download also our media kit: [http://www.sensorsportal.com/DOWNLOADS/Media\\_Kit\\_2012.pdf](http://www.sensorsportal.com/DOWNLOADS/Media_Kit_2012.pdf)

***Digital Sensors and Sensor Systems: Practical Design*** will greatly benefit undergraduate and at PhD students, engineers, scientists and researchers in both industry and academia. It is especially suited as a reference guide for practitioners, working for Original Equipment Manufacturers (OEM) electronics market (electronics/hardware), sensor industry, and using commercial-off-the-shelf components, as well as anyone facing new challenges in technologies, and those involved in the design and creation of new digital sensors and sensor systems, including smart and/or intelligent sensors for physical or chemical, electrical or non-electrical quantities.



*"It is an outstanding and most completed practical guide about how to deal with frequency, period, duty-cycle, time interval, pulse width modulated, phase-shift and pulse number output sensors and transducers and quickly create various low-cost digital sensors and sensor systems ..."* (from a review)

Order online:

[http://www.sensorsportal.com/HTML/BOOKSTORE/Digital\\_Sensors.htm](http://www.sensorsportal.com/HTML/BOOKSTORE/Digital_Sensors.htm)



[www.sensorsportal.com](http://www.sensorsportal.com)